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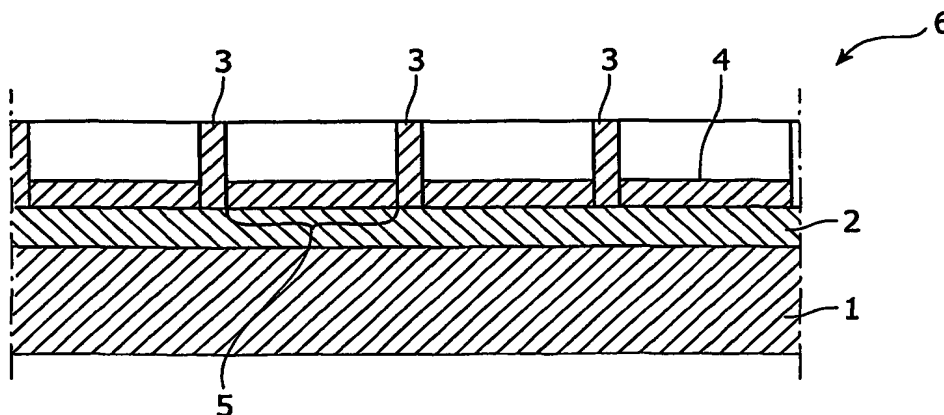
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(54) Title: THIN FILM PATTERNING ARRANGEMENT



(57) Abstract: A thin film patterning arrangement (6), comprising a substrate (1) and barriers (3) arranged to partition a surface of the substrate (1) into sub-areas (5) is disclosed. Said surface is of a polymeric material, and is coated with an at least partly inorganic coating (2). Thin film material (4) is preferably deposited on said thin film patterning arrangement (6).

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